Preferred Device

Silicon Controlled Rectifiers

Reverse Blocking Thyristors

Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supplies; or wherever half-wave silicon gate-controlled, solid-state devices are needed.

Features

- Glass Passivated Junctions with Center Gate Geometry for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Blocking Voltage to 800 Volts
- Pb-Free Packages are Available*



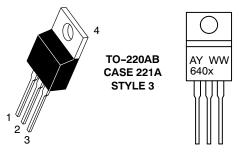
ON Semiconductor®

http://onsemi.com

SCRs 16 AMPERES RMS 50 thru 800 VOLTS



MARKING DIAGRAM



x = 0, 1, 2, 3, 4 or 5 A = Assembly Location

Y = Year WW = Work Week

PIN ASSIGNMENT		
1	Cathode	
2	Anode	
3	Gate	
4	Anode	

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS* (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off-State Voltage (Note 1)	$V_{DRM,}$		V
$(T_J = -40 \text{ to } 125^{\circ}\text{C}, \text{ Sine Wave } 50 \text{ to } 60 \text{ Hz}; \text{ Gate Open})$	V_{RRM}		
2N6400		50	
2N6401		100	
2N6402		200	
2N6403		400	
2N6404		600	
2N6405		800	
On-State Current RMS (180° Conduction Angles; T _C = 100°C)	I _{T(RMS)}	16	Α
Average On-State Current (180° Conduction Angles; T _C = 100°C)	I _{T(AV)}	10	Α
Peak Non-repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, T _J = 90°C)	I _{TSM}	160	Α
Circuit Fusing Considerations (t = 8.3 ms)	I ² t	145	A ² s
Forward Peak Gate Power (Pulse Width ≤ 1.0 μs, T _C = 100°C)	P _{GM}	20	W
Forward Average Gate Power (t = 8.3 ms, T _C = 100°C)	P _{G(AV)}	0.5	W
Forward Peak Gate Current (Pulse Width ≤ 1.0 μs, T _C = 100°C)	I _{GM}	2.0	Α
Operating Junction Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic		Max	Unit
Thermal Resistance, Junction-to-Case		1.5	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8 in from Case for 10 Seconds	T _L	260	°C

Critical Rate-of-Rise of Off-State Voltage (V_D = Rated V_{DRM}, Exponential Waveform)

Characteristic		Min	Тур	Max	Unit
FF CHARACTERISTICS					
*Peak Repetitive Forward or Reverse Blocking Current $(V_{AK} = \text{Rated V}_{DRM} \text{ or V}_{RRM}, \text{ Gate Open})$ $T_J = 25^{\circ}\text{C}$ $T_J = 125^{\circ}\text{C}$	I _{DRM} , I _{RRM}	- -	- -	10 2.0	μA mA
N CHARACTERISTICS					
*Peak Forward On-State Voltage (I_{TM} = 32 A Peak, Pulse Width \leq 1 ms, Duty Cycle \leq 2%)	V_{TM}	-	-	1.7	V
*Gate Trigger Current (Continuous dc) $T_C = 25^{\circ}C$ $(V_D = 12 \text{ Vdc}, R_L = 100 \Omega)$ $T_C = -40^{\circ}C$	I _{GT}	- -	9.0	30 60	mA
*Gate Trigger Voltage (Continuous dc) $ (V_D = 12 \text{ Vdc}, \ R_L = 100 \ \Omega) \qquad \qquad T_C = 25^{\circ}\text{C} \\ T_C = -40^{\circ}\text{C} $	V _{GT}		0.7	1.5 2.5	V
Gate Non-Trigger Voltage (V_D = 12 Vdc, R_L = 100 Ω), T_C = +125°C		0.2	-	_	V
*Holding Current $T_C = 25^{\circ}C$ (V _D = 12 Vdc, Initiating Current = 200 mA, Gate Open) * $T_C = -40^{\circ}C$	lΗ	-	18 -	40 60	mA
Turn-On Time (I _{TM} = 16 A, I _{GT} = 40 mAdc, V _D = Rated V _{DRM})		-	1.0	_	μs
Turn-Off Time (I _{TM} = 16 A, I _R = 16 A, V _D = Rated V _{DRM})	t _q	-	15 35	-	μS

^{*}Indicates JEDEC Registered Data.

 $T_J = +125^{\circ}C$

dv/dt

50

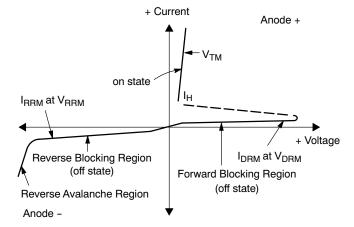
V/μs

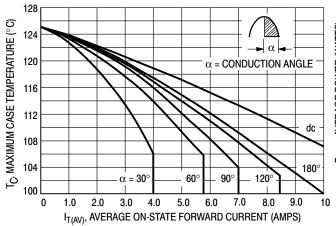
V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

16

Voltage Current Characteristic of SCR

Symbol	Parameter
V _{DRM}	Peak Repetitive Off State Forward Voltage
I _{DRM}	Peak Forward Blocking Current
V_{RRM}	Peak Repetitive Off State Reverse Voltage
I _{RRM}	Peak Reverse Blocking Current
V_{TM}	Peak On State Voltage
IH	Holding Current





P_(AV), AVERAGE POWER (WATTS) 14 120° $T_J\approx 125^{\circ}C$ 909 12 10 $\alpha = 30^{\circ}$ 8.0 6.0 4.0 2.0 α = CONDUCTION ANGLE 7.0 3.0 4.0 5.0 6.0 8.0 9.0 I_{T(AV)}, AVERAGE ON-STATE FORWARD CURRENT (AMPS)

180°

Figure 1. Average Current Derating

Figure 2. Maximum On-State Power Dissipation

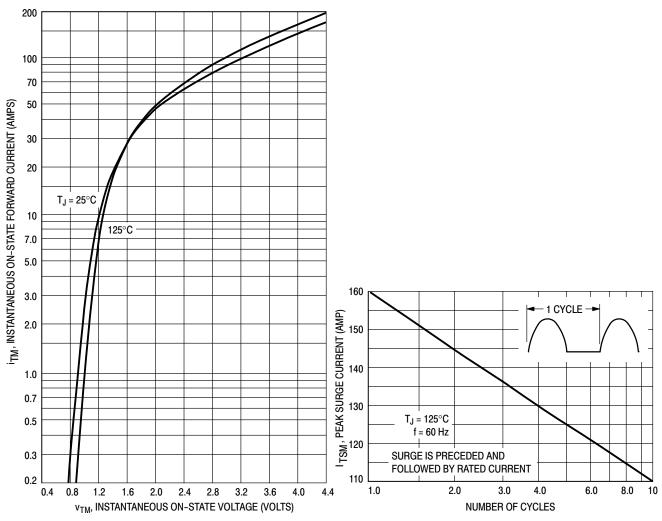


Figure 3. On-State Characteristics

Figure 4. Maximum Non-Repetitive Surge Current

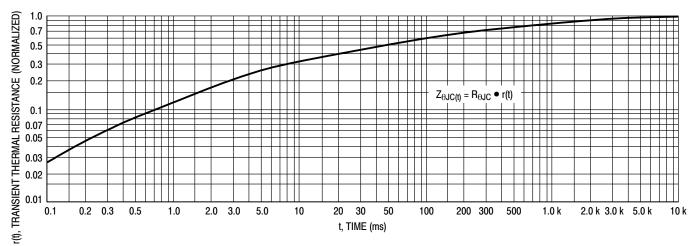


Figure 5. Thermal Response

TYPICAL CHARACTERISTICS

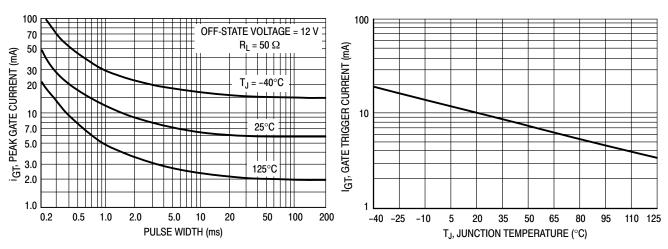


Figure 6. Typical Gate Trigger Current versus Pulse Width

Figure 7. Typical Gate Trigger Current versus Junction Temperature

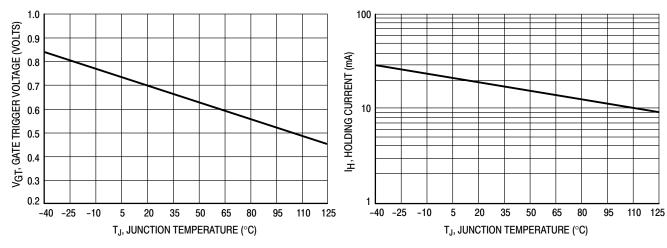


Figure 8. Typical Gate Trigger Voltage versus Junction Temperature

Figure 9. Typical Holding Current versus Junction Temperature

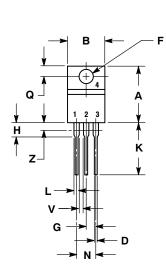
ORDERING INFORMATION

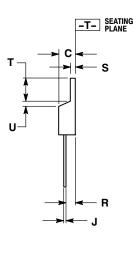
Device	Package	Shipping [†]	
2N6400	TO-220AB		
2N6400G	TO-220AB (Pb-Free)		
2N6401	TO-220AB		
2N6401G	TO-220AB (Pb-Free)	FOO Heile / Days	
2N6402	TO-220AB	500 Units / Box	
2N6402G	TO-220AB (Pb-Free)		
2N6403	TO-220AB		
2N6403G	TO-220AB (Pb-Free)		
2N6403TG	TO-220AB (Pb-Free)	50 Units / Rail	
2N6404	TO-220AB		
2N6404G	TO-220AB (Pb-Free)	FOO Heite / Davi	
2N6405	TO-220AB	500 Units / Box	
2N6405G	TO-220AB (Pb-Free)		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

TO-220AB CASE 221A-07 ISSUE AA





NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		INCHES MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.022	0.36	0.55
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
C	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 3:

PIN 1. CATHODE

2. ANODE 3. GATE

ANODE

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